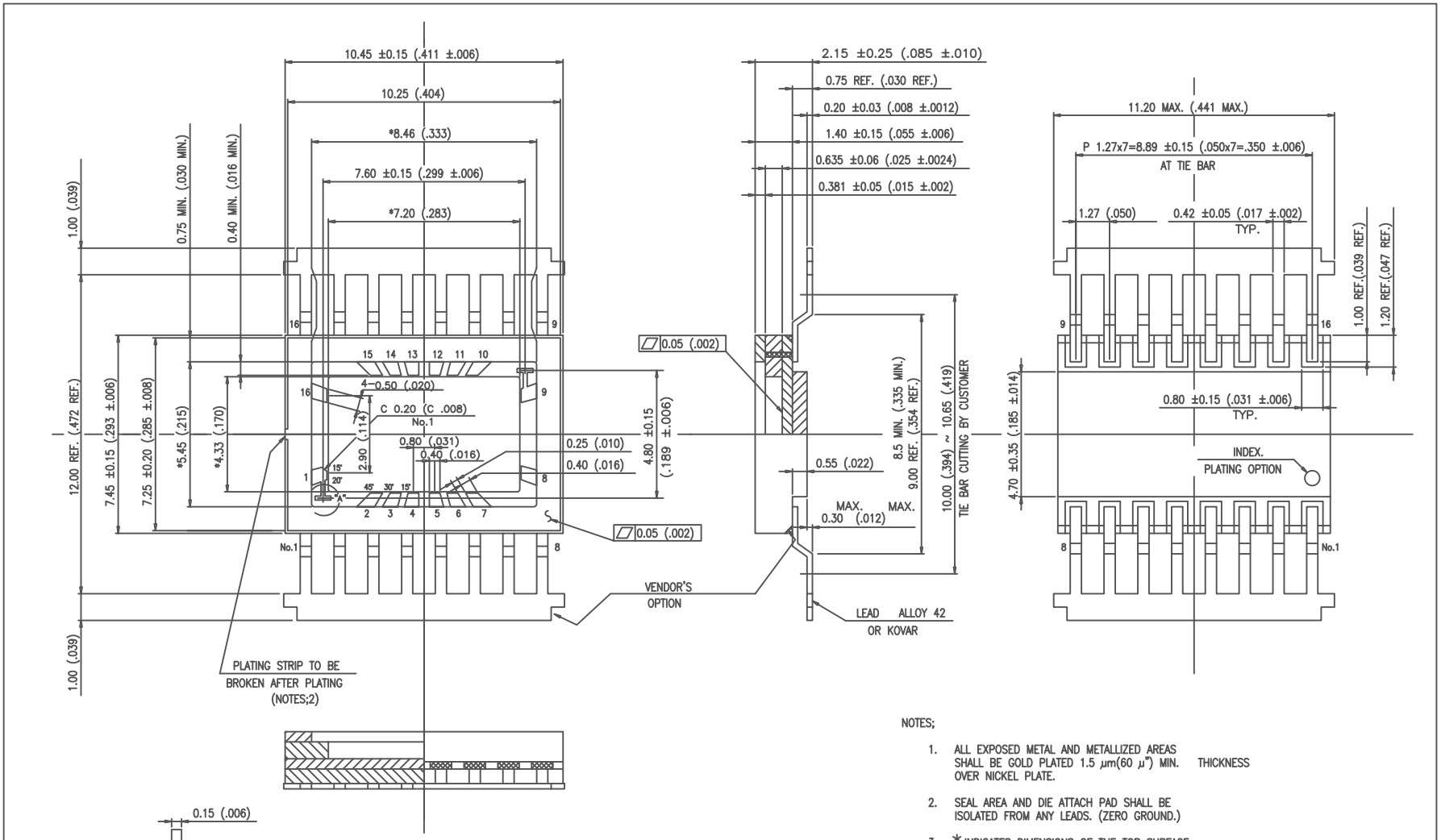
SSM P/N CSO01602



NOTES;

1. ALL EXPOSED METAL AND METALLIZED AREAS SHALL BE GOLD PLATED 1.5 μm(60 μ") MIN. THICKNESS OVER NICKEL PLATE.
2. SEAL AREA AND DIE ATTACH PAD SHALL BE ISOLATED FROM ANY LEADS. (ZERO GROUND.)
3. * INDICATES DIMENSIONS OF THE TOP SURFACE.

CONTROLLED 3-11-03

S=0
D=0

FPL-16-41

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
16 LEAD S.O.PACKAGE	± 0.13 (±.005) THIRD ANGLE PROJECTION	S.M	U.F / K.H	M.S	MAR.16.'99
SCALE 10/1	MATERIAL KYOCERA A-440				
KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. PB-F88151			SHEET 1/1

PB-F86651-B (P00-16F) MOD.

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226